

# Global 3D-IC Packaging Market Research Report 2024(Status and Outlook)

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## Abstracts

### Report Overview

3D-IC (Three-Dimensional Integrated Circuit) packaging is an advanced packaging technology used in the semiconductor industry to vertically stack multiple integrated circuit (IC) dies or chips. It involves stacking and interconnecting multiple IC chips within a single package, allowing for increased integration, improved performance, and reduced form factor of electronic devices.

This report provides a deep insight into the global 3D-IC Packaging market covering all its essential aspects. This ranges from a macro overview of the market to micro details of the market size, competitive landscape, development trend, niche market, key market drivers and challenges, SWOT analysis, value chain analysis, etc.

The analysis helps the reader to shape the competition within the industries and strategies for the competitive environment to enhance the potential profit. Furthermore, it provides a simple framework for evaluating and accessing the position of the business organization. The report structure also focuses on the competitive landscape of the Global 3D-IC Packaging Market, this report introduces in detail the market share, market performance, product situation, operation situation, etc. of the main players, which helps the readers in the industry to identify the main competitors and deeply understand the competition pattern of the market.

In a word, this report is a must-read for industry players, investors, researchers, consultants, business strategists, and all those who have any kind of stake or are planning to foray into the 3D-IC Packaging market in any manner.

## Global 3D-IC Packaging Market: Market Segmentation Analysis

The research report includes specific segments by region (country), manufacturers, Type, and Application. Market segmentation creates subsets of a market based on product type, end-user or application, Geographic, and other factors. By understanding the market segments, the decision-maker can leverage this targeting in the product, sales, and marketing strategies. Market segments can power your product development cycles by informing how you create product offerings for different segments.

### Key Company

Synopsys

Cadence

XMC

United Microelectronics Corp

TSMC

SPIL

STMicroelectronics

ASE Group

Amkor Technology

Intel Corporation

GlobalFoundries

Invensas

Toshiba Corporation

Micron Technology

Xilinx

Market Segmentation (by Type)

TSV

TGV

Silicon Interposer

Market Segmentation (by Application)

Consumer Electronics

Medical Devices

Automotive

Others

Geographic Segmentation

North America (USA, Canada, Mexico)

Europe (Germany, UK, France, Russia, Italy, Rest of Europe)

Asia-Pacific (China, Japan, South Korea, India, Southeast Asia, Rest of Asia-Pacific)

South America (Brazil, Argentina, Columbia, Rest of South America)

The Middle East and Africa (Saudi Arabia, UAE, Egypt, Nigeria, South Africa, Rest of MEA)

Key Benefits of This Market Research:

Industry drivers, restraints, and opportunities covered in the study

Neutral perspective on the market performance

Recent industry trends and developments

Competitive landscape & strategies of key players

Potential & niche segments and regions exhibiting promising growth covered

Historical, current, and projected market size, in terms of value

In-depth analysis of the 3D-IC Packaging Market

Overview of the regional outlook of the 3D-IC Packaging Market:

#### Key Reasons to Buy this Report:

Access to date statistics compiled by our researchers. These provide you with historical and forecast data, which is analyzed to tell you why your market is set to change

This enables you to anticipate market changes to remain ahead of your competitors

You will be able to copy data from the Excel spreadsheet straight into your marketing plans, business presentations, or other strategic documents

The concise analysis, clear graph, and table format will enable you to pinpoint the information you require quickly

Provision of market value (USD Billion) data for each segment and sub-segment

Indicates the region and segment that is expected to witness the fastest growth as well as to dominate the market

Analysis by geography highlighting the consumption of the product/service in the region as well as indicating the factors that are affecting the market within each region

Competitive landscape which incorporates the market ranking of the major players, along with new service/product launches, partnerships, business expansions, and acquisitions in the past five years of companies profiled

Extensive company profiles comprising of company overview, company insights, product benchmarking, and SWOT analysis for the major market players

The current as well as the future market outlook of the industry concerning recent developments which involve growth opportunities and drivers as well as challenges and restraints of both emerging as well as developed regions

Includes in-depth analysis of the market from various perspectives through Porter's five forces analysis

Provides insight into the market through Value Chain

Market dynamics scenario, along with growth opportunities of the market in the years to come

6-month post-sales analyst support

## Customization of the Report

In case of any queries or customization requirements, please connect with our sales team, who will ensure that your requirements are met.

## Chapter Outline

Chapter 1 mainly introduces the statistical scope of the report, market division standards, and market research methods.

Chapter 2 is an executive summary of different market segments (by region, product type, application, etc), including the market size of each market segment, future development potential, and so on. It offers a high-level view of the current state of the 3D-IC Packaging Market and its likely evolution in the short to mid-term, and long term.

Chapter 3 makes a detailed analysis of the market's competitive landscape of the market and provides the market share, capacity, output, price, latest development plan,

merger, and acquisition information of the main manufacturers in the market.

Chapter 4 is the analysis of the whole market industrial chain, including the upstream and downstream of the industry, as well as Porter's five forces analysis.

Chapter 5 introduces the latest developments of the market, the driving factors and restrictive factors of the market, the challenges and risks faced by manufacturers in the industry, and the analysis of relevant policies in the industry.

Chapter 6 provides the analysis of various market segments according to product types, covering the market size and development potential of each market segment, to help readers find the blue ocean market in different market segments.

Chapter 7 provides the analysis of various market segments according to application, covering the market size and development potential of each market segment, to help readers find the blue ocean market in different downstream markets.

Chapter 8 provides a quantitative analysis of the market size and development potential of each region and its main countries and introduces the market development, future development prospects, market space, and capacity of each country in the world.

Chapter 9 introduces the basic situation of the main companies in the market in detail, including product sales revenue, sales volume, price, gross profit margin, market share, product introduction, recent development, etc.

Chapter 10 provides a quantitative analysis of the market size and development potential of each region in the next five years.

Chapter 11 provides a quantitative analysis of the market size and development potential of each market segment (product type and application) in the next five years.

Chapter 12 is the main points and conclusions of the report.

## Contents

### **1 RESEARCH METHODOLOGY AND STATISTICAL SCOPE**

- 1.1 Market Definition and Statistical Scope of 3D-IC Packaging
- 1.2 Key Market Segments
  - 1.2.1 3D-IC Packaging Segment by Type
  - 1.2.2 3D-IC Packaging Segment by Application
- 1.3 Methodology & Sources of Information
  - 1.3.1 Research Methodology
  - 1.3.2 Research Process
  - 1.3.3 Market Breakdown and Data Triangulation
  - 1.3.4 Base Year
  - 1.3.5 Report Assumptions & Caveats

### **2 3D-IC PACKAGING MARKET OVERVIEW**

- 2.1 Global Market Overview
  - 2.1.1 Global 3D-IC Packaging Market Size (M USD) Estimates and Forecasts (2019-2030)
  - 2.1.2 Global 3D-IC Packaging Sales Estimates and Forecasts (2019-2030)
- 2.2 Market Segment Executive Summary
- 2.3 Global Market Size by Region

### **3 3D-IC PACKAGING MARKET COMPETITIVE LANDSCAPE**

- 3.1 Global 3D-IC Packaging Sales by Manufacturers (2019-2024)
- 3.2 Global 3D-IC Packaging Revenue Market Share by Manufacturers (2019-2024)
- 3.3 3D-IC Packaging Market Share by Company Type (Tier 1, Tier 2, and Tier 3)
- 3.4 Global 3D-IC Packaging Average Price by Manufacturers (2019-2024)
- 3.5 Manufacturers 3D-IC Packaging Sales Sites, Area Served, Product Type
- 3.6 3D-IC Packaging Market Competitive Situation and Trends
  - 3.6.1 3D-IC Packaging Market Concentration Rate
  - 3.6.2 Global 5 and 10 Largest 3D-IC Packaging Players Market Share by Revenue
  - 3.6.3 Mergers & Acquisitions, Expansion

### **4 3D-IC PACKAGING INDUSTRY CHAIN ANALYSIS**

- 4.1 3D-IC Packaging Industry Chain Analysis

- 4.2 Market Overview of Key Raw Materials
- 4.3 Midstream Market Analysis
- 4.4 Downstream Customer Analysis

## **5 THE DEVELOPMENT AND DYNAMICS OF 3D-IC PACKAGING MARKET**

- 5.1 Key Development Trends
- 5.2 Driving Factors
- 5.3 Market Challenges
- 5.4 Market Restraints
- 5.5 Industry News
  - 5.5.1 New Product Developments
  - 5.5.2 Mergers & Acquisitions
  - 5.5.3 Expansions
  - 5.5.4 Collaboration/Supply Contracts
- 5.6 Industry Policies

## **6 3D-IC PACKAGING MARKET SEGMENTATION BY TYPE**

- 6.1 Evaluation Matrix of Segment Market Development Potential (Type)
- 6.2 Global 3D-IC Packaging Sales Market Share by Type (2019-2024)
- 6.3 Global 3D-IC Packaging Market Size Market Share by Type (2019-2024)
- 6.4 Global 3D-IC Packaging Price by Type (2019-2024)

## **7 3D-IC PACKAGING MARKET SEGMENTATION BY APPLICATION**

- 7.1 Evaluation Matrix of Segment Market Development Potential (Application)
- 7.2 Global 3D-IC Packaging Market Sales by Application (2019-2024)
- 7.3 Global 3D-IC Packaging Market Size (M USD) by Application (2019-2024)
- 7.4 Global 3D-IC Packaging Sales Growth Rate by Application (2019-2024)

## **8 3D-IC PACKAGING MARKET SEGMENTATION BY REGION**

- 8.1 Global 3D-IC Packaging Sales by Region
  - 8.1.1 Global 3D-IC Packaging Sales by Region
  - 8.1.2 Global 3D-IC Packaging Sales Market Share by Region
- 8.2 North America
  - 8.2.1 North America 3D-IC Packaging Sales by Country
  - 8.2.2 U.S.

- 8.2.3 Canada
- 8.2.4 Mexico
- 8.3 Europe
  - 8.3.1 Europe 3D-IC Packaging Sales by Country
  - 8.3.2 Germany
  - 8.3.3 France
  - 8.3.4 U.K.
  - 8.3.5 Italy
  - 8.3.6 Russia
- 8.4 Asia Pacific
  - 8.4.1 Asia Pacific 3D-IC Packaging Sales by Region
  - 8.4.2 China
  - 8.4.3 Japan
  - 8.4.4 South Korea
  - 8.4.5 India
  - 8.4.6 Southeast Asia
- 8.5 South America
  - 8.5.1 South America 3D-IC Packaging Sales by Country
  - 8.5.2 Brazil
  - 8.5.3 Argentina
  - 8.5.4 Columbia
- 8.6 Middle East and Africa
  - 8.6.1 Middle East and Africa 3D-IC Packaging Sales by Region
  - 8.6.2 Saudi Arabia
  - 8.6.3 UAE
  - 8.6.4 Egypt
  - 8.6.5 Nigeria
  - 8.6.6 South Africa

## **9 KEY COMPANIES PROFILE**

- 9.1 Synopsys
  - 9.1.1 Synopsys 3D-IC Packaging Basic Information
  - 9.1.2 Synopsys 3D-IC Packaging Product Overview
  - 9.1.3 Synopsys 3D-IC Packaging Product Market Performance
  - 9.1.4 Synopsys Business Overview
  - 9.1.5 Synopsys 3D-IC Packaging SWOT Analysis
  - 9.1.6 Synopsys Recent Developments
- 9.2 Cadence

- 9.2.1 Cadence 3D-IC Packaging Basic Information
- 9.2.2 Cadence 3D-IC Packaging Product Overview
- 9.2.3 Cadence 3D-IC Packaging Product Market Performance
- 9.2.4 Cadence Business Overview
- 9.2.5 Cadence 3D-IC Packaging SWOT Analysis
- 9.2.6 Cadence Recent Developments
- 9.3 XMC
  - 9.3.1 XMC 3D-IC Packaging Basic Information
  - 9.3.2 XMC 3D-IC Packaging Product Overview
  - 9.3.3 XMC 3D-IC Packaging Product Market Performance
  - 9.3.4 XMC 3D-IC Packaging SWOT Analysis
  - 9.3.5 XMC Business Overview
  - 9.3.6 XMC Recent Developments
- 9.4 United Microelectronics Corp
  - 9.4.1 United Microelectronics Corp 3D-IC Packaging Basic Information
  - 9.4.2 United Microelectronics Corp 3D-IC Packaging Product Overview
  - 9.4.3 United Microelectronics Corp 3D-IC Packaging Product Market Performance
  - 9.4.4 United Microelectronics Corp Business Overview
  - 9.4.5 United Microelectronics Corp Recent Developments
- 9.5 TSMC
  - 9.5.1 TSMC 3D-IC Packaging Basic Information
  - 9.5.2 TSMC 3D-IC Packaging Product Overview
  - 9.5.3 TSMC 3D-IC Packaging Product Market Performance
  - 9.5.4 TSMC Business Overview
  - 9.5.5 TSMC Recent Developments
- 9.6 SPIL
  - 9.6.1 SPIL 3D-IC Packaging Basic Information
  - 9.6.2 SPIL 3D-IC Packaging Product Overview
  - 9.6.3 SPIL 3D-IC Packaging Product Market Performance
  - 9.6.4 SPIL Business Overview
  - 9.6.5 SPIL Recent Developments
- 9.7 STMicroelectronics
  - 9.7.1 STMicroelectronics 3D-IC Packaging Basic Information
  - 9.7.2 STMicroelectronics 3D-IC Packaging Product Overview
  - 9.7.3 STMicroelectronics 3D-IC Packaging Product Market Performance
  - 9.7.4 STMicroelectronics Business Overview
  - 9.7.5 STMicroelectronics Recent Developments
- 9.8 ASE Group
  - 9.8.1 ASE Group 3D-IC Packaging Basic Information

- 9.8.2 ASE Group 3D-IC Packaging Product Overview
- 9.8.3 ASE Group 3D-IC Packaging Product Market Performance
- 9.8.4 ASE Group Business Overview
- 9.8.5 ASE Group Recent Developments
- 9.9 Amkor Technology
  - 9.9.1 Amkor Technology 3D-IC Packaging Basic Information
  - 9.9.2 Amkor Technology 3D-IC Packaging Product Overview
  - 9.9.3 Amkor Technology 3D-IC Packaging Product Market Performance
  - 9.9.4 Amkor Technology Business Overview
  - 9.9.5 Amkor Technology Recent Developments
- 9.10 Intel Corporation
  - 9.10.1 Intel Corporation 3D-IC Packaging Basic Information
  - 9.10.2 Intel Corporation 3D-IC Packaging Product Overview
  - 9.10.3 Intel Corporation 3D-IC Packaging Product Market Performance
  - 9.10.4 Intel Corporation Business Overview
  - 9.10.5 Intel Corporation Recent Developments
- 9.11 GlobalFoundries
  - 9.11.1 GlobalFoundries 3D-IC Packaging Basic Information
  - 9.11.2 GlobalFoundries 3D-IC Packaging Product Overview
  - 9.11.3 GlobalFoundries 3D-IC Packaging Product Market Performance
  - 9.11.4 GlobalFoundries Business Overview
  - 9.11.5 GlobalFoundries Recent Developments
- 9.12 Invensas
  - 9.12.1 Invensas 3D-IC Packaging Basic Information
  - 9.12.2 Invensas 3D-IC Packaging Product Overview
  - 9.12.3 Invensas 3D-IC Packaging Product Market Performance
  - 9.12.4 Invensas Business Overview
  - 9.12.5 Invensas Recent Developments
- 9.13 Toshiba Corporation
  - 9.13.1 Toshiba Corporation 3D-IC Packaging Basic Information
  - 9.13.2 Toshiba Corporation 3D-IC Packaging Product Overview
  - 9.13.3 Toshiba Corporation 3D-IC Packaging Product Market Performance
  - 9.13.4 Toshiba Corporation Business Overview
  - 9.13.5 Toshiba Corporation Recent Developments
- 9.14 Micron Technology
  - 9.14.1 Micron Technology 3D-IC Packaging Basic Information
  - 9.14.2 Micron Technology 3D-IC Packaging Product Overview
  - 9.14.3 Micron Technology 3D-IC Packaging Product Market Performance
  - 9.14.4 Micron Technology Business Overview

9.14.5 Micron Technology Recent Developments

9.15 Xilinx

9.15.1 Xilinx 3D-IC Packaging Basic Information

9.15.2 Xilinx 3D-IC Packaging Product Overview

9.15.3 Xilinx 3D-IC Packaging Product Market Performance

9.15.4 Xilinx Business Overview

9.15.5 Xilinx Recent Developments

## **10 3D-IC PACKAGING MARKET FORECAST BY REGION**

10.1 Global 3D-IC Packaging Market Size Forecast

10.2 Global 3D-IC Packaging Market Forecast by Region

10.2.1 North America Market Size Forecast by Country

10.2.2 Europe 3D-IC Packaging Market Size Forecast by Country

10.2.3 Asia Pacific 3D-IC Packaging Market Size Forecast by Region

10.2.4 South America 3D-IC Packaging Market Size Forecast by Country

10.2.5 Middle East and Africa Forecasted Consumption of 3D-IC Packaging by Country

## **11 FORECAST MARKET BY TYPE AND BY APPLICATION (2025-2030)**

11.1 Global 3D-IC Packaging Market Forecast by Type (2025-2030)

11.1.1 Global Forecasted Sales of 3D-IC Packaging by Type (2025-2030)

11.1.2 Global 3D-IC Packaging Market Size Forecast by Type (2025-2030)

11.1.3 Global Forecasted Price of 3D-IC Packaging by Type (2025-2030)

11.2 Global 3D-IC Packaging Market Forecast by Application (2025-2030)

11.2.1 Global 3D-IC Packaging Sales (K Units) Forecast by Application

11.2.2 Global 3D-IC Packaging Market Size (M USD) Forecast by Application (2025-2030)

## **12 CONCLUSION AND KEY FINDINGS**

## List Of Tables

### LIST OF TABLES

- Table 1. Introduction of the Type
- Table 2. Introduction of the Application
- Table 3. Market Size (M USD) Segment Executive Summary
- Table 4. 3D-IC Packaging Market Size Comparison by Region (M USD)
- Table 5. Global 3D-IC Packaging Sales (K Units) by Manufacturers (2019-2024)
- Table 6. Global 3D-IC Packaging Sales Market Share by Manufacturers (2019-2024)
- Table 7. Global 3D-IC Packaging Revenue (M USD) by Manufacturers (2019-2024)
- Table 8. Global 3D-IC Packaging Revenue Share by Manufacturers (2019-2024)
- Table 9. Company Type (Tier 1, Tier 2, and Tier 3) & (based on the Revenue in 3D-IC Packaging as of 2022)
- Table 10. Global Market 3D-IC Packaging Average Price (USD/Unit) of Key Manufacturers (2019-2024)
- Table 11. Manufacturers 3D-IC Packaging Sales Sites and Area Served
- Table 12. Manufacturers 3D-IC Packaging Product Type
- Table 13. Global 3D-IC Packaging Manufacturers Market Concentration Ratio (CR5 and HHI)
- Table 14. Mergers & Acquisitions, Expansion Plans
- Table 15. Industry Chain Map of 3D-IC Packaging
- Table 16. Market Overview of Key Raw Materials
- Table 17. Midstream Market Analysis
- Table 18. Downstream Customer Analysis
- Table 19. Key Development Trends
- Table 20. Driving Factors
- Table 21. 3D-IC Packaging Market Challenges
- Table 22. Global 3D-IC Packaging Sales by Type (K Units)
- Table 23. Global 3D-IC Packaging Market Size by Type (M USD)
- Table 24. Global 3D-IC Packaging Sales (K Units) by Type (2019-2024)
- Table 25. Global 3D-IC Packaging Sales Market Share by Type (2019-2024)
- Table 26. Global 3D-IC Packaging Market Size (M USD) by Type (2019-2024)
- Table 27. Global 3D-IC Packaging Market Size Share by Type (2019-2024)
- Table 28. Global 3D-IC Packaging Price (USD/Unit) by Type (2019-2024)
- Table 29. Global 3D-IC Packaging Sales (K Units) by Application
- Table 30. Global 3D-IC Packaging Market Size by Application
- Table 31. Global 3D-IC Packaging Sales by Application (2019-2024) & (K Units)
- Table 32. Global 3D-IC Packaging Sales Market Share by Application (2019-2024)

- Table 33. Global 3D-IC Packaging Sales by Application (2019-2024) & (M USD)
- Table 34. Global 3D-IC Packaging Market Share by Application (2019-2024)
- Table 35. Global 3D-IC Packaging Sales Growth Rate by Application (2019-2024)
- Table 36. Global 3D-IC Packaging Sales by Region (2019-2024) & (K Units)
- Table 37. Global 3D-IC Packaging Sales Market Share by Region (2019-2024)
- Table 38. North America 3D-IC Packaging Sales by Country (2019-2024) & (K Units)
- Table 39. Europe 3D-IC Packaging Sales by Country (2019-2024) & (K Units)
- Table 40. Asia Pacific 3D-IC Packaging Sales by Region (2019-2024) & (K Units)
- Table 41. South America 3D-IC Packaging Sales by Country (2019-2024) & (K Units)
- Table 42. Middle East and Africa 3D-IC Packaging Sales by Region (2019-2024) & (K Units)
- Table 43. Synopsys 3D-IC Packaging Basic Information
- Table 44. Synopsys 3D-IC Packaging Product Overview
- Table 45. Synopsys 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 46. Synopsys Business Overview
- Table 47. Synopsys 3D-IC Packaging SWOT Analysis
- Table 48. Synopsys Recent Developments
- Table 49. Cadence 3D-IC Packaging Basic Information
- Table 50. Cadence 3D-IC Packaging Product Overview
- Table 51. Cadence 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 52. Cadence Business Overview
- Table 53. Cadence 3D-IC Packaging SWOT Analysis
- Table 54. Cadence Recent Developments
- Table 55. XMC 3D-IC Packaging Basic Information
- Table 56. XMC 3D-IC Packaging Product Overview
- Table 57. XMC 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 58. XMC 3D-IC Packaging SWOT Analysis
- Table 59. XMC Business Overview
- Table 60. XMC Recent Developments
- Table 61. United Microelectronics Corp 3D-IC Packaging Basic Information
- Table 62. United Microelectronics Corp 3D-IC Packaging Product Overview
- Table 63. United Microelectronics Corp 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 64. United Microelectronics Corp Business Overview
- Table 65. United Microelectronics Corp Recent Developments
- Table 66. TSMC 3D-IC Packaging Basic Information

- Table 67. TSMC 3D-IC Packaging Product Overview
- Table 68. TSMC 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 69. TSMC Business Overview
- Table 70. TSMC Recent Developments
- Table 71. SPIL 3D-IC Packaging Basic Information
- Table 72. SPIL 3D-IC Packaging Product Overview
- Table 73. SPIL 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 74. SPIL Business Overview
- Table 75. SPIL Recent Developments
- Table 76. STMicroelectronics 3D-IC Packaging Basic Information
- Table 77. STMicroelectronics 3D-IC Packaging Product Overview
- Table 78. STMicroelectronics 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 79. STMicroelectronics Business Overview
- Table 80. STMicroelectronics Recent Developments
- Table 81. ASE Group 3D-IC Packaging Basic Information
- Table 82. ASE Group 3D-IC Packaging Product Overview
- Table 83. ASE Group 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 84. ASE Group Business Overview
- Table 85. ASE Group Recent Developments
- Table 86. Amkor Technology 3D-IC Packaging Basic Information
- Table 87. Amkor Technology 3D-IC Packaging Product Overview
- Table 88. Amkor Technology 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 89. Amkor Technology Business Overview
- Table 90. Amkor Technology Recent Developments
- Table 91. Intel Corporation 3D-IC Packaging Basic Information
- Table 92. Intel Corporation 3D-IC Packaging Product Overview
- Table 93. Intel Corporation 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 94. Intel Corporation Business Overview
- Table 95. Intel Corporation Recent Developments
- Table 96. GlobalFoundries 3D-IC Packaging Basic Information
- Table 97. GlobalFoundries 3D-IC Packaging Product Overview
- Table 98. GlobalFoundries 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)

- Table 99. GlobalFoundries Business Overview
- Table 100. GlobalFoundries Recent Developments
- Table 101. Invensas 3D-IC Packaging Basic Information
- Table 102. Invensas 3D-IC Packaging Product Overview
- Table 103. Invensas 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 104. Invensas Business Overview
- Table 105. Invensas Recent Developments
- Table 106. Toshiba Corporation 3D-IC Packaging Basic Information
- Table 107. Toshiba Corporation 3D-IC Packaging Product Overview
- Table 108. Toshiba Corporation 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 109. Toshiba Corporation Business Overview
- Table 110. Toshiba Corporation Recent Developments
- Table 111. Micron Technology 3D-IC Packaging Basic Information
- Table 112. Micron Technology 3D-IC Packaging Product Overview
- Table 113. Micron Technology 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 114. Micron Technology Business Overview
- Table 115. Micron Technology Recent Developments
- Table 116. Xilinx 3D-IC Packaging Basic Information
- Table 117. Xilinx 3D-IC Packaging Product Overview
- Table 118. Xilinx 3D-IC Packaging Sales (K Units), Revenue (M USD), Price (USD/Unit) and Gross Margin (2019-2024)
- Table 119. Xilinx Business Overview
- Table 120. Xilinx Recent Developments
- Table 121. Global 3D-IC Packaging Sales Forecast by Region (2025-2030) & (K Units)
- Table 122. Global 3D-IC Packaging Market Size Forecast by Region (2025-2030) & (M USD)
- Table 123. North America 3D-IC Packaging Sales Forecast by Country (2025-2030) & (K Units)
- Table 124. North America 3D-IC Packaging Market Size Forecast by Country (2025-2030) & (M USD)
- Table 125. Europe 3D-IC Packaging Sales Forecast by Country (2025-2030) & (K Units)
- Table 126. Europe 3D-IC Packaging Market Size Forecast by Country (2025-2030) & (M USD)
- Table 127. Asia Pacific 3D-IC Packaging Sales Forecast by Region (2025-2030) & (K Units)
- Table 128. Asia Pacific 3D-IC Packaging Market Size Forecast by Region (2025-2030)

& (M USD)

Table 129. South America 3D-IC Packaging Sales Forecast by Country (2025-2030) & (K Units)

Table 130. South America 3D-IC Packaging Market Size Forecast by Country (2025-2030) & (M USD)

Table 131. Middle East and Africa 3D-IC Packaging Consumption Forecast by Country (2025-2030) & (Units)

Table 132. Middle East and Africa 3D-IC Packaging Market Size Forecast by Country (2025-2030) & (M USD)

Table 133. Global 3D-IC Packaging Sales Forecast by Type (2025-2030) & (K Units)

Table 134. Global 3D-IC Packaging Market Size Forecast by Type (2025-2030) & (M USD)

Table 135. Global 3D-IC Packaging Price Forecast by Type (2025-2030) & (USD/Unit)

Table 136. Global 3D-IC Packaging Sales (K Units) Forecast by Application (2025-2030)

Table 137. Global 3D-IC Packaging Market Size Forecast by Application (2025-2030) & (M USD)

## List Of Figures

### LIST OF FIGURES

- Figure 1. Product Picture of 3D-IC Packaging
- Figure 2. Data Triangulation
- Figure 3. Key Caveats
- Figure 4. Global 3D-IC Packaging Market Size (M USD), 2019-2030
- Figure 5. Global 3D-IC Packaging Market Size (M USD) (2019-2030)
- Figure 6. Global 3D-IC Packaging Sales (K Units) & (2019-2030)
- Figure 7. Evaluation Matrix of Segment Market Development Potential (Type)
- Figure 8. Evaluation Matrix of Segment Market Development Potential (Application)
- Figure 9. Evaluation Matrix of Regional Market Development Potential
- Figure 10. 3D-IC Packaging Market Size by Country (M USD)
- Figure 11. 3D-IC Packaging Sales Share by Manufacturers in 2023
- Figure 12. Global 3D-IC Packaging Revenue Share by Manufacturers in 2023
- Figure 13. 3D-IC Packaging Market Share by Company Type (Tier 1, Tier 2 and Tier 3): 2023
- Figure 14. Global Market 3D-IC Packaging Average Price (USD/Unit) of Key Manufacturers in 2023
- Figure 15. The Global 5 and 10 Largest Players: Market Share by 3D-IC Packaging Revenue in 2023
- Figure 16. Evaluation Matrix of Segment Market Development Potential (Type)
- Figure 17. Global 3D-IC Packaging Market Share by Type
- Figure 18. Sales Market Share of 3D-IC Packaging by Type (2019-2024)
- Figure 19. Sales Market Share of 3D-IC Packaging by Type in 2023
- Figure 20. Market Size Share of 3D-IC Packaging by Type (2019-2024)
- Figure 21. Market Size Market Share of 3D-IC Packaging by Type in 2023
- Figure 22. Evaluation Matrix of Segment Market Development Potential (Application)
- Figure 23. Global 3D-IC Packaging Market Share by Application
- Figure 24. Global 3D-IC Packaging Sales Market Share by Application (2019-2024)
- Figure 25. Global 3D-IC Packaging Sales Market Share by Application in 2023
- Figure 26. Global 3D-IC Packaging Market Share by Application (2019-2024)
- Figure 27. Global 3D-IC Packaging Market Share by Application in 2023
- Figure 28. Global 3D-IC Packaging Sales Growth Rate by Application (2019-2024)
- Figure 29. Global 3D-IC Packaging Sales Market Share by Region (2019-2024)
- Figure 30. North America 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 31. North America 3D-IC Packaging Sales Market Share by Country in 2023

- Figure 32. U.S. 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 33. Canada 3D-IC Packaging Sales (K Units) and Growth Rate (2019-2024)
- Figure 34. Mexico 3D-IC Packaging Sales (Units) and Growth Rate (2019-2024)
- Figure 35. Europe 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 36. Europe 3D-IC Packaging Sales Market Share by Country in 2023
- Figure 37. Germany 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 38. France 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 39. U.K. 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 40. Italy 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 41. Russia 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 42. Asia Pacific 3D-IC Packaging Sales and Growth Rate (K Units)
- Figure 43. Asia Pacific 3D-IC Packaging Sales Market Share by Region in 2023
- Figure 44. China 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 45. Japan 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 46. South Korea 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 47. India 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 48. Southeast Asia 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 49. South America 3D-IC Packaging Sales and Growth Rate (K Units)
- Figure 50. South America 3D-IC Packaging Sales Market Share by Country in 2023
- Figure 51. Brazil 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 52. Argentina 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 53. Columbia 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 54. Middle East and Africa 3D-IC Packaging Sales and Growth Rate (K Units)
- Figure 55. Middle East and Africa 3D-IC Packaging Sales Market Share by Region in 2023
- Figure 56. Saudi Arabia 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 57. UAE 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 58. Egypt 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 59. Nigeria 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 60. South Africa 3D-IC Packaging Sales and Growth Rate (2019-2024) & (K Units)
- Figure 61. Global 3D-IC Packaging Sales Forecast by Volume (2019-2030) & (K Units)
- Figure 62. Global 3D-IC Packaging Market Size Forecast by Value (2019-2030) & (M USD)
- Figure 63. Global 3D-IC Packaging Sales Market Share Forecast by Type (2025-2030)
- Figure 64. Global 3D-IC Packaging Market Share Forecast by Type (2025-2030)

Figure 65. Global 3D-IC Packaging Sales Forecast by Application (2025-2030)

Figure 66. Global 3D-IC Packaging Market Share Forecast by Application (2025-2030)

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